

MOSFET

StrongIRFET™ 2 Power-Transistor

Features

- Optimized for a wide range of applications
- N-Channel, normal level
- 100% avalanche tested
- Pb-free lead plating; RoHS compliant
- Halogen-free according to IEC61249-2-21

Product validation

Qualified according to JEDEC Standard

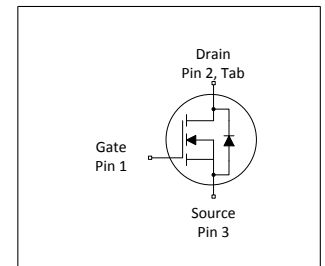
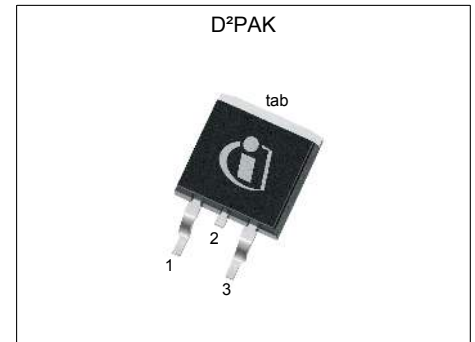


Table 1 Key Performance Parameters

| Parameter | Value | Unit |
|------------------|-------|------------|
| V_{DS} | 80 | V |
| $R_{DS(on),max}$ | 1.95 | m Ω |
| I_D | 166 | A |
| Q_{oss} | 145 | nC |
| Q_G | 124 | nC |



RoHS

| Type / Ordering Code | Package | Marking | Related Links |
|----------------------|------------|----------|---------------|
| IPB019N08NF2S | PG-TO263-3 | 019N08NS | - |

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1 Maximum ratings

at $T_A=25\text{ °C}$, unless otherwise specified

Table 2 Maximum ratings

| Parameter | Symbol | Values | | | Unit | Note / Test Condition |
|--|-------------------|--------|------|-------------------------|------|--|
| | | Min. | Typ. | Max. | | |
| Continuous drain current ¹⁾ | I_D | - | - | 166 128 128 31 | A | $V_{GS}=10\text{ V}$, $T_C=25\text{ °C}$ $V_{GS}=10\text{ V}$, $T_C=100\text{ °C}$ $V_{GS}=6\text{ V}$, $T_C=100\text{ °C}$ $V_{GS}=10\text{ V}$, $T_A=25\text{ °C}$, $R_{thJA}=40\text{ °C/W}^2)$ |
| Pulsed drain current ³⁾ | $I_{D,pulse}$ | - | - | 664 | A | $T_A=25\text{ °C}$ |
| Avalanche energy, single pulse ⁴⁾ | E_{AS} | - | - | 593 | mJ | $I_D=100\text{ A}$, $R_{GS}=25\text{ }\Omega$ |
| Gate source voltage | V_{GS} | -20 | - | 20 | V | - |
| Power dissipation | P_{tot} | - | - | 250 3.8 | W | $T_C=25\text{ °C}$ $T_A=25\text{ °C}$, $R_{thJA}=40\text{ °C/W}^2)$ |
| Operating and storage temperature | T_j , T_{stg} | -55 | - | 175 | °C | - |

2 Thermal characteristics

Table 3 Thermal characteristics

| Parameter | Symbol | Values | | | Unit | Note / Test Condition |
|--|------------|--------|------|------|------|-----------------------|
| | | Min. | Typ. | Max. | | |
| Thermal resistance, junction - case | R_{thJC} | - | - | 0.6 | °C/W | - |
| Thermal resistance, junction - ambient, 6 cm ² cooling area ²⁾ | R_{thJA} | - | - | 40 | °C/W | - |
| Thermal resistance, junction - ambient, minimal footprint | R_{thJA} | - | - | 62 | °C/W | - |

¹⁾ Rating refers to the product only with datasheet specified absolute maximum values, maintaining case temperature as specified. For other case temperatures please refer to Diagram 2. De-rating will be required based on the actual environmental conditions.

²⁾ Device on 40 mm x 40 mm x 1.5 mm epoxy PCB FR4 with 6 cm² (one layer, 70 µm thick) copper area for drain connection. PCB is vertical in still air.

³⁾ See Diagram 3 for more detailed information

⁴⁾ See Diagram 13 for more detailed information

3 Electrical characteristics
 at $T_j=25\text{ °C}$, unless otherwise specified

Table 4 Static characteristics

| Parameter | Symbol | Values | | | Unit | Note / Test Condition |
|----------------------------------|---------------|--------|------------|-------------|------------------|---|
| | | Min. | Typ. | Max. | | |
| Drain-source breakdown voltage | $V_{(BR)DSS}$ | 80 | - | - | V | $V_{GS}=0\text{ V}$, $I_D=1\text{ mA}$ |
| Gate threshold voltage | $V_{GS(th)}$ | 2.2 | 3.0 | 3.8 | V | $V_{DS}=V_{GS}$, $I_D=194\text{ }\mu\text{A}$ |
| Zero gate voltage drain current | I_{DSS} | - | 0.1 10 | 1 100 | μA | $V_{DS}=80\text{ V}$, $V_{GS}=0\text{ V}$, $T_j=25\text{ °C}$ $V_{DS}=80\text{ V}$, $V_{GS}=0\text{ V}$, $T_j=125\text{ °C}$ |
| Gate-source leakage current | I_{GSS} | - | 10 | 100 | nA | $V_{GS}=20\text{ V}$, $V_{DS}=0\text{ V}$ |
| Drain-source on-state resistance | $R_{DS(on)}$ | - | 1.6 2.0 | 1.95 2.6 | $\text{m}\Omega$ | $V_{GS}=10\text{ V}$, $I_D=100\text{ A}$ $V_{GS}=6\text{ V}$, $I_D=50\text{ A}$ |
| Gate resistance | R_G | - | 1.2 | - | Ω | - |
| Transconductance ¹⁾ | g_{fs} | 108 | - | - | S | $ V_{DS} \geq 2 I_D R_{DS(on)max}$, $I_D=100\text{ A}$ |

Table 5 Dynamic characteristics

| Parameter | Symbol | Values | | | Unit | Note / Test Condition |
|------------------------------|--------------|--------|------|------|------|---|
| | | Min. | Typ. | Max. | | |
| Input capacitance | C_{iss} | - | 8700 | - | pF | $V_{GS}=0\text{ V}$, $V_{DS}=40\text{ V}$, $f=1\text{ MHz}$ |
| Output capacitance | C_{oss} | - | 1400 | - | pF | $V_{GS}=0\text{ V}$, $V_{DS}=40\text{ V}$, $f=1\text{ MHz}$ |
| Reverse transfer capacitance | C_{rss} | - | 61 | - | pF | $V_{GS}=0\text{ V}$, $V_{DS}=40\text{ V}$, $f=1\text{ MHz}$ |
| Turn-on delay time | $t_{d(on)}$ | - | 21 | - | ns | $V_{DD}=40\text{ V}$, $V_{GS}=10\text{ V}$, $I_D=100\text{ A}$, $R_{G,ext}=1.6\text{ }\Omega$ |
| Rise time | t_r | - | 62 | - | ns | $V_{DD}=40\text{ V}$, $V_{GS}=10\text{ V}$, $I_D=100\text{ A}$, $R_{G,ext}=1.6\text{ }\Omega$ |
| Turn-off delay time | $t_{d(off)}$ | - | 50 | - | ns | $V_{DD}=40\text{ V}$, $V_{GS}=10\text{ V}$, $I_D=100\text{ A}$, $R_{G,ext}=1.6\text{ }\Omega$ |
| Fall time | t_f | - | 26 | - | ns | $V_{DD}=40\text{ V}$, $V_{GS}=10\text{ V}$, $I_D=100\text{ A}$, $R_{G,ext}=1.6\text{ }\Omega$ |

Table 6 Gate charge characteristics²⁾

| Parameter | Symbol | Values | | | Unit | Note / Test Condition |
|---------------------------------|---------------|--------|------|------|------|--|
| | | Min. | Typ. | Max. | | |
| Gate to source charge | Q_{gs} | - | 40 | - | nC | $V_{DD}=40\text{ V}$, $I_D=100\text{ A}$, $V_{GS}=0\text{ to }10\text{ V}$ |
| Gate charge at threshold | $Q_{g(th)}$ | - | 26 | - | nC | $V_{DD}=40\text{ V}$, $I_D=100\text{ A}$, $V_{GS}=0\text{ to }10\text{ V}$ |
| Gate to drain charge | Q_{gd} | - | 26 | - | nC | $V_{DD}=40\text{ V}$, $I_D=100\text{ A}$, $V_{GS}=0\text{ to }10\text{ V}$ |
| Switching charge | Q_{sw} | - | 40 | - | nC | $V_{DD}=40\text{ V}$, $I_D=100\text{ A}$, $V_{GS}=0\text{ to }10\text{ V}$ |
| Gate charge total ¹⁾ | Q_g | - | 124 | 186 | nC | $V_{DD}=40\text{ V}$, $I_D=100\text{ A}$, $V_{GS}=0\text{ to }10\text{ V}$ |
| Gate plateau voltage | $V_{plateau}$ | - | 4.6 | - | V | $V_{DD}=40\text{ V}$, $I_D=100\text{ A}$, $V_{GS}=0\text{ to }10\text{ V}$ |
| Gate charge total, sync. FET | $Q_{g(sync)}$ | - | 107 | - | nC | $V_{DS}=0.1\text{ V}$, $V_{GS}=0\text{ to }10\text{ V}$ |
| Output charge | Q_{oss} | - | 145 | - | nC | $V_{DS}=40\text{ V}$, $V_{GS}=0\text{ V}$ |

¹⁾ Defined by design. Not subject to production test.

²⁾ See "Gate charge waveforms" for parameter definition

Table 7 Reverse diode

| Parameter | Symbol | Values | | | Unit | Note / Test Condition |
|----------------------------------|---------------|--------|------|------|------|---|
| | | Min. | Typ. | Max. | | |
| Diode continuous forward current | I_S | - | - | 131 | A | $T_C=25\text{ °C}$ |
| Diode pulse current | $I_{S,pulse}$ | - | - | 664 | A | $T_C=25\text{ °C}$ |
| Diode forward voltage | V_{SD} | - | 0.88 | 1.2 | V | $V_{GS}=0\text{ V}, I_F=100\text{ A}, T_j=25\text{ °C}$ |
| Reverse recovery time | t_{rr} | - | 44 | - | ns | $V_R=40\text{ V}, I_F=100\text{ A}, di_F/dt=500\text{ A}/\mu\text{s}$ |
| Reverse recovery charge | Q_{rr} | - | 285 | - | nC | $V_R=40\text{ V}, I_F=100\text{ A}, di_F/dt=500\text{ A}/\mu\text{s}$ |

4 Electrical characteristics diagrams

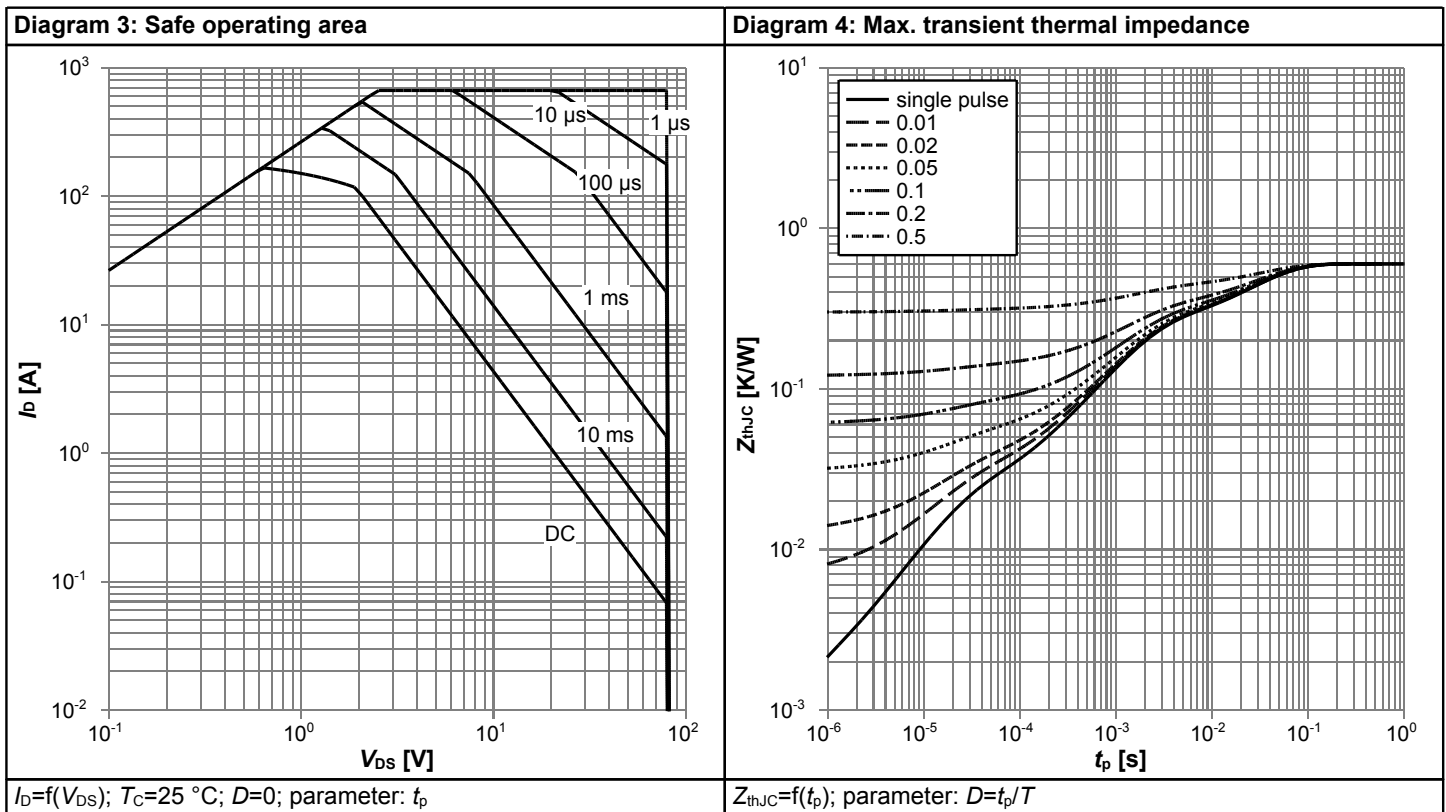
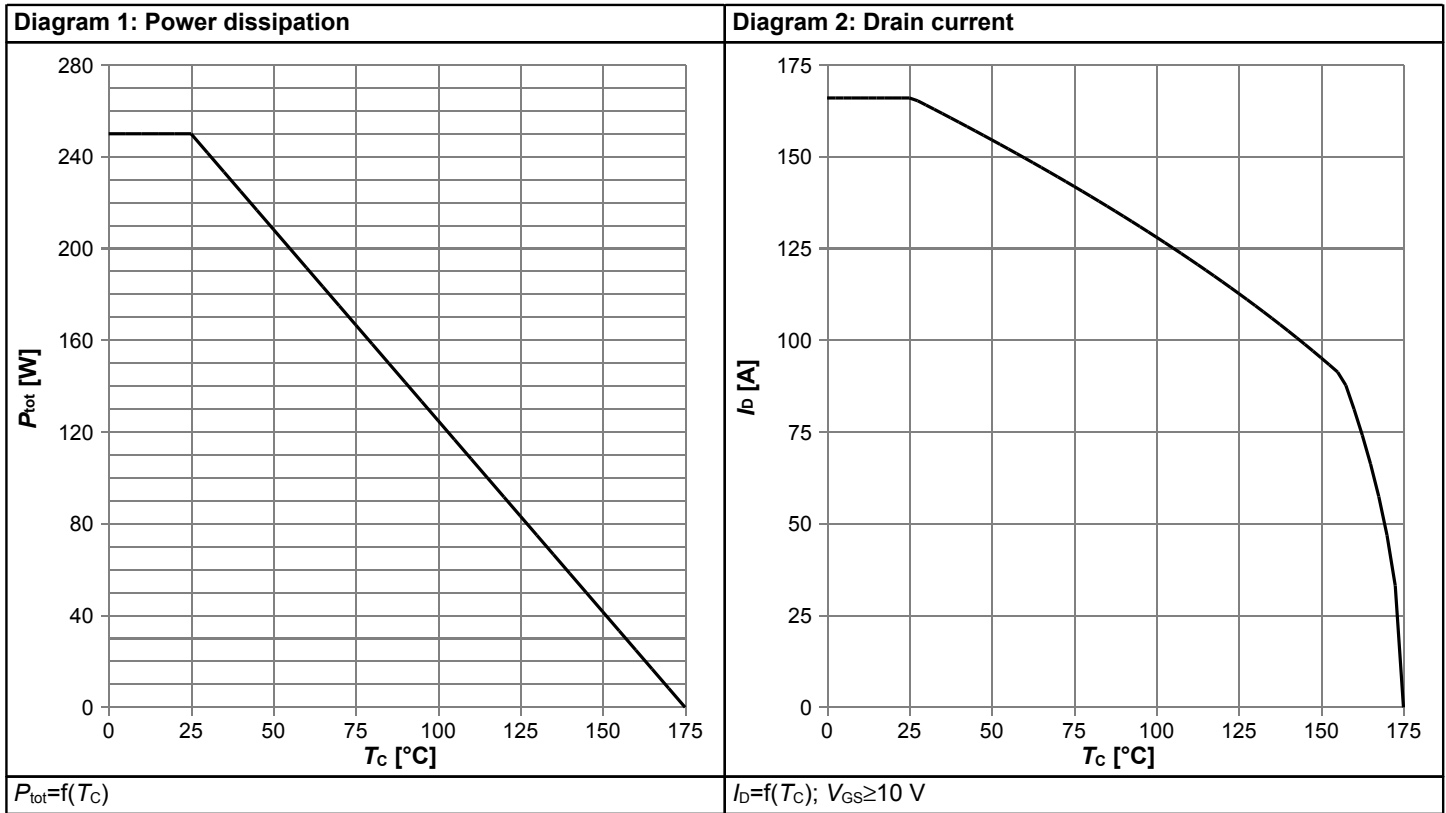
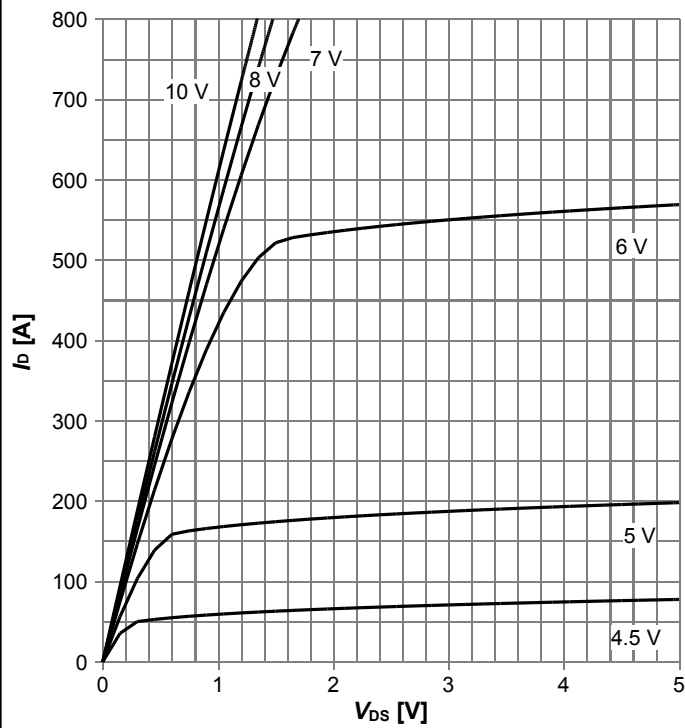
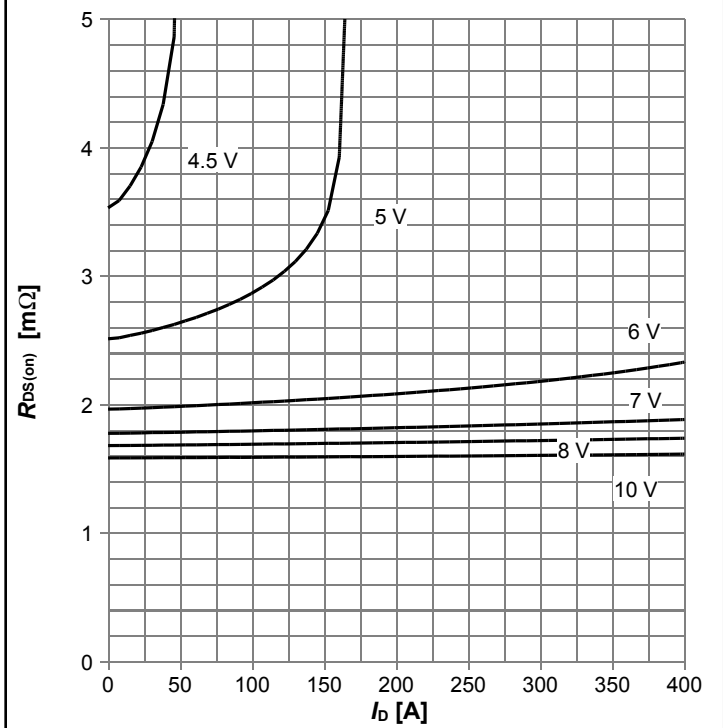


Diagram 5: Typ. output characteristics



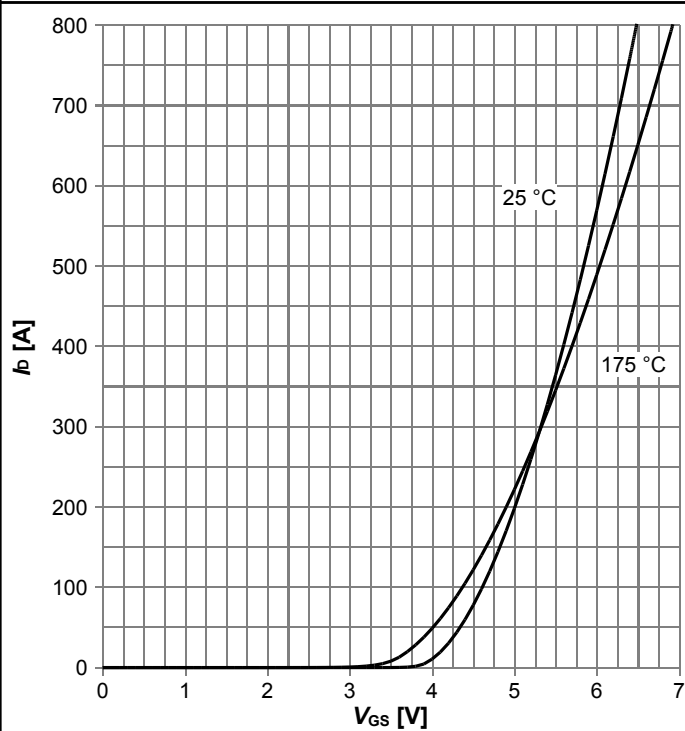
$I_D = f(V_{DS}), T_j = 25\text{ °C};$ parameter: V_{GS}

Diagram 6: Typ. drain-source on resistance



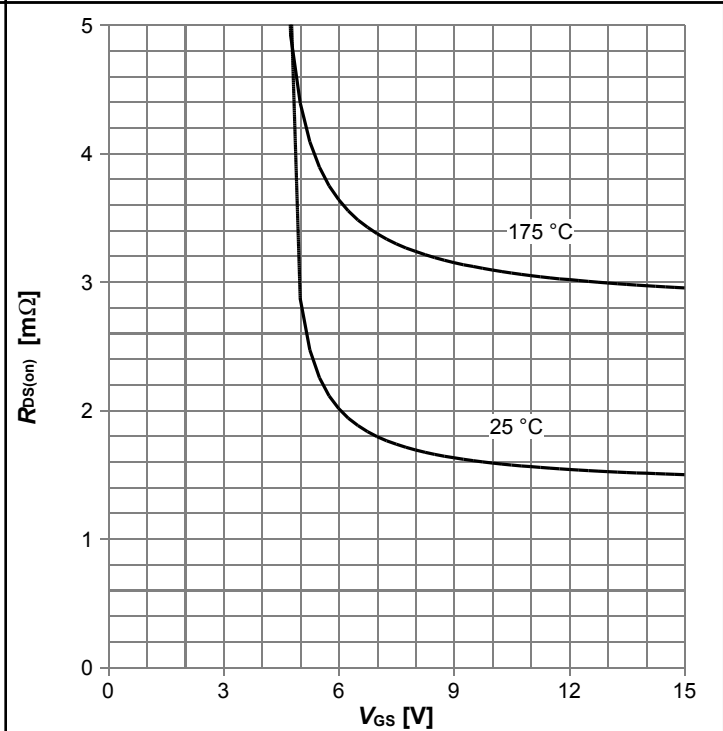
$R_{DS(on)} = f(I_D), T_j = 25\text{ °C};$ parameter: V_{GS}

Diagram 7: Typ. transfer characteristics



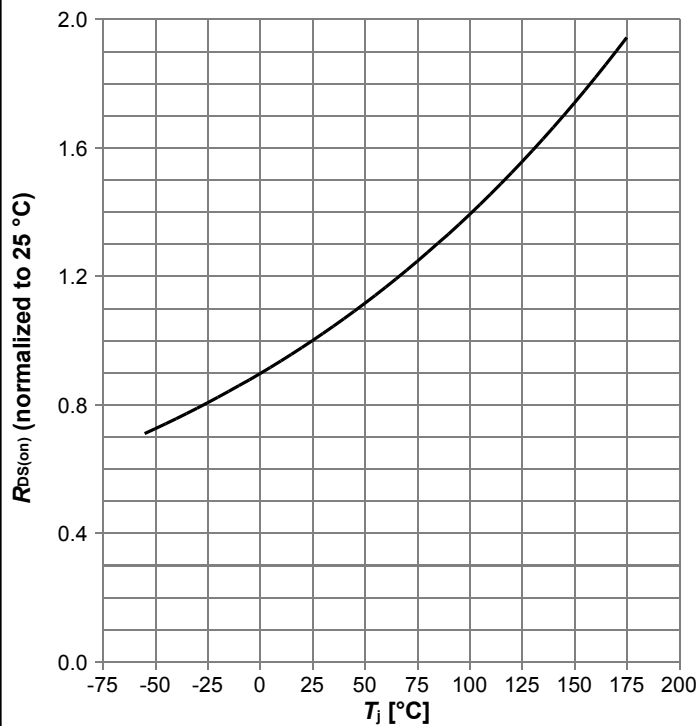
$I_D = f(V_{GS}), |V_{DS}| > 2|I_D|R_{DS(on)max};$ parameter: T_j

Diagram 8: Typ. drain-source on resistance



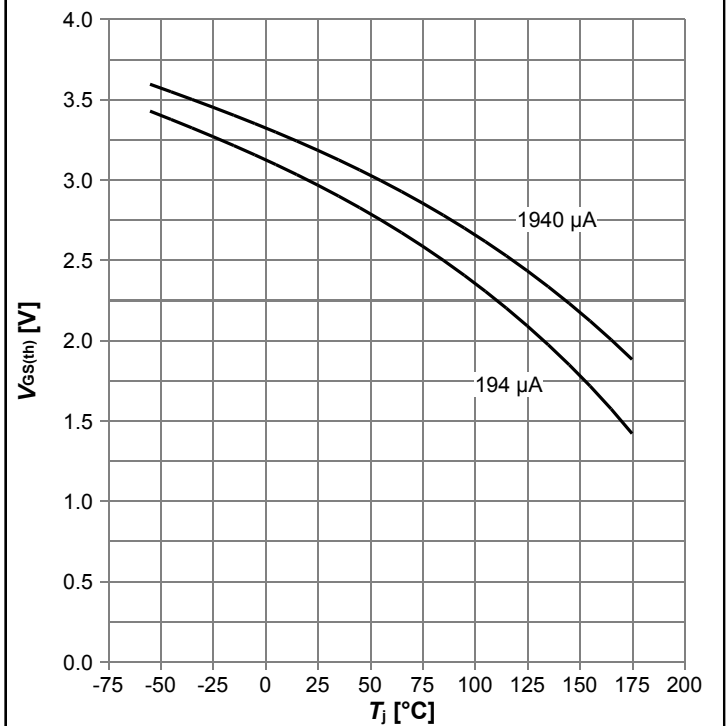
$R_{DS(on)} = f(V_{GS}), I_D = 100\text{ A};$ parameter: T_j

Diagram 9: Normalized drain-source on resistance



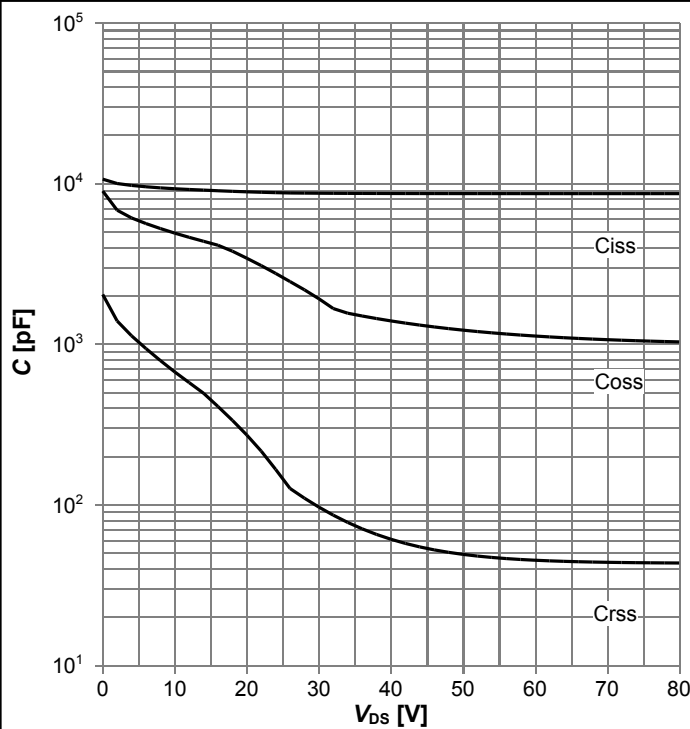
$R_{DS(on)}=f(T_j)$, $I_D=100$ A, $V_{GS}=10$ V

Diagram 10: Typ. gate threshold voltage



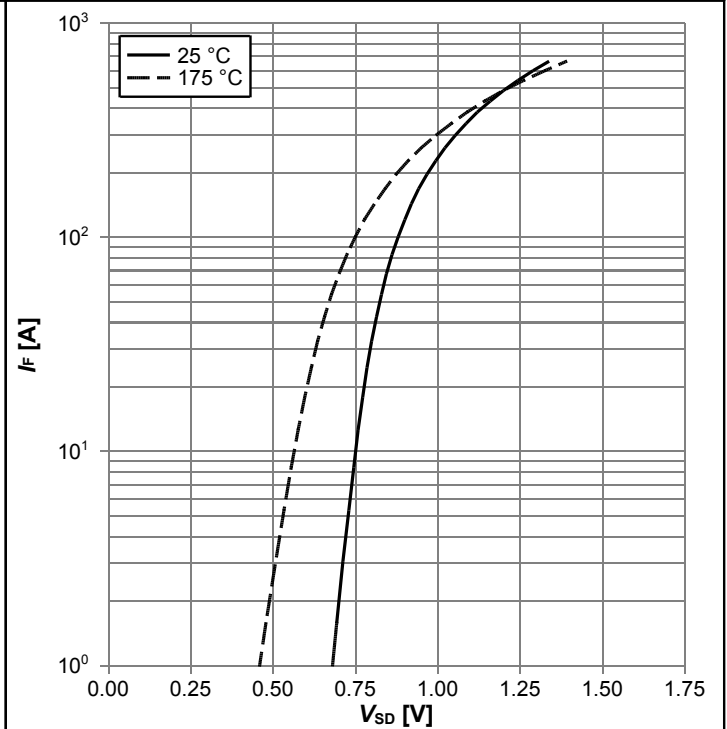
$V_{GS(th)}=f(T_j)$, $V_{GS}=V_{DS}$; parameter: I_D

Diagram 11: Typ. capacitances



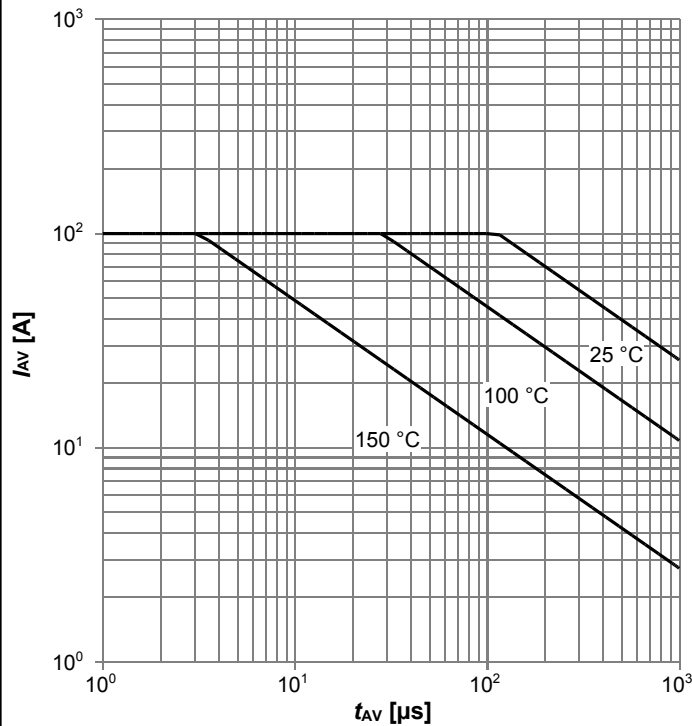
$C=f(V_{DS})$; $V_{GS}=0$ V; $f=1$ MHz

Diagram 12: Typ. forward characteristics of reverse diode



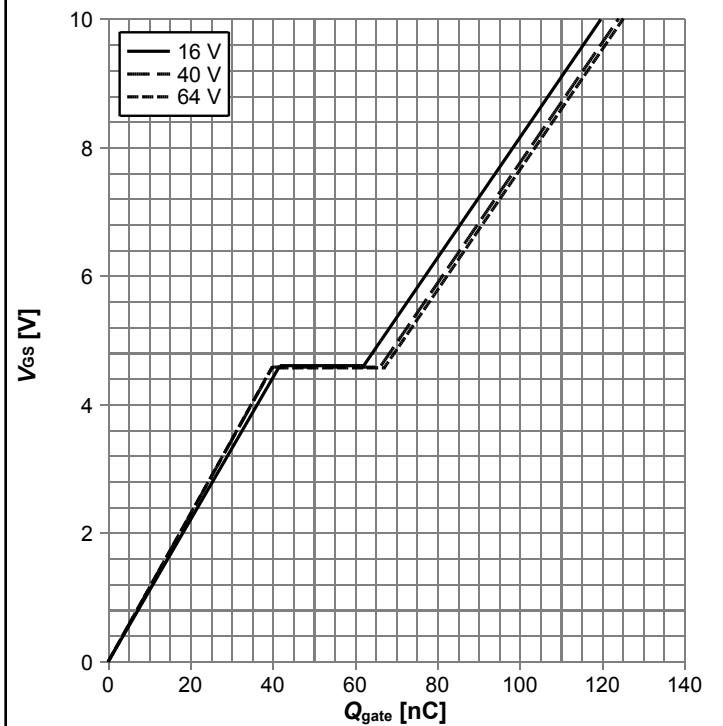
$I_F=f(V_{SD})$; parameter: T_j

Diagram 13: Avalanche characteristics



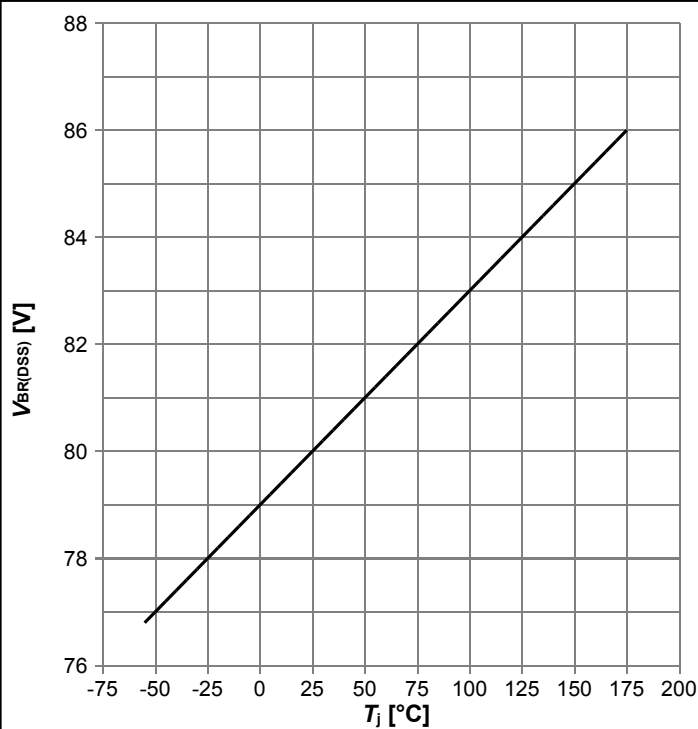
$I_{AS}=f(t_{AV}); R_{GS}=25 \Omega$; parameter: $T_{j,start}$

Diagram 14: Typ. gate charge



$V_{GS}=f(Q_{gate}), I_D=100$ A pulsed, $T_j=25$ °C; parameter: V_{DD}

Diagram 15: Drain-source breakdown voltage

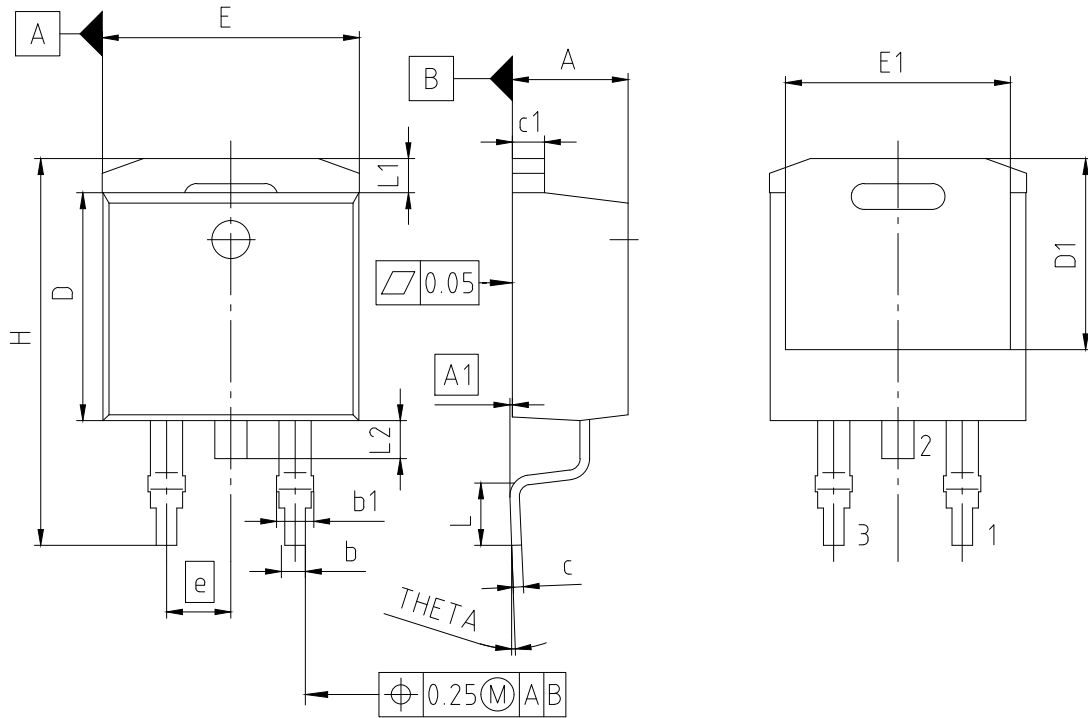


$V_{BR(DSS)}=f(T_j); I_D=1$ mA

Diagram Gate charge waveforms



5 Package Outlines



| PACKAGE - GROUP NUMBER: PG-T0263-3-U02 | | |
|---|-------------|-------|
| DIMENSIONS | MILLIMETERS | |
| | MIN. | MAX. |
| A | 4.06 | 4.83 |
| A1 | 0.00 | 0.25 |
| b | 0.51 | 1.00 |
| b1 | 1.07 | 1.78 |
| c | 0.30 | 0.73 |
| c1 | 1.14 | 1.65 |
| D | 8.38 | 9.65 |
| D1 | 6.60 | 7.50 |
| E | 9.65 | 10.67 |
| E1 | 6.22 | 8.70 |
| e | 2.54 | |
| N | 3 | |
| H | 14.60 | 15.88 |
| L | 1.52 | 2.60 |
| L1 | 1.05 | 1.68 |
| L2 | 1.35 | 1.78 |
| THETA | -9.00° | 8.00° |

PG-T0263-3-10: OPTIONAL
 5:1

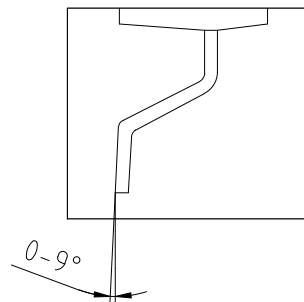


Figure 1 Outline PG-T0263-3, dimensions in mm

Revision History

IPB019N08NF2S

Revision: 2022-09-23, Rev. 2.0

Previous Revision

| Revision | Date | Subjects (major changes since last revision) |
|----------|------------|--|
| 2.0 | 2022-09-23 | Release of final version |

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